

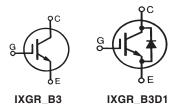
Preliminary Technical Information

GenX3[™] 600V IGBTs

(Electrically Isolated Back Surface)

Medium-Speed Low-Vsat PT IGBTs 5-40 kHz Switching

IXGR48N60B3 IXGR48N60B3D1



IXGR_B3

C25 $V_{CE(sat)} \leq 2.1V$ = 116ns **t**_{fi(typ)}

 $\boldsymbol{V}_{\text{CES}}$

=



Symbol	Test Conditions	Maximum Ratings			
V _{CES}	$T_c = 25^{\circ}C$ to $150^{\circ}C$	600	V		
V _{CGR}	$T_{J} = 25^{\circ}C$ to 150°C, $R_{GE} = 1M\Omega$	600	V		
V _{ges}	Continuous	± 20	V		
V _{gem}	Transient	± 30	V		
C ₂₅ C ₁₁₀	$T_{c} = 25^{\circ}C$ $T_{c} = 110^{\circ}C$	60 27	A A		
I _{F110} I _{СМ}	T _c = 110°C (48N60B3D1) T _c = 25°C, 1ms	27 280	A A		
SSOA	$V_{_{GE}} = 15V, T_{_{VJ}} = 125^{\circ}C, R_{_{G}} = 5\Omega$	I _{CM} = 120	A		
(RBSOA)	Clamped Inductive Load	$@ \le V_{CE}$			
P _c	T _c = 25°C	150	W		
T		-55 +150	°C		
T _{JM}		150	°C		
T _{stg}		-55 +150	°C		
TL	1.6mm (0.062 in.) from Case for 10s	300	°C		
	Plastic Body for 10 seconds	260	°C		
F _c	Mounting Force	20120 / 4.527	N/lb.		
V _{ISOL}	50/60 Hz, RM, t = 1min	2500	V~		
Weight		5	g		

Chara Min.	acteristic Typ.	Values Max.
600		V
3.0		5.5 V
		25 μΑ
		1.75 mA
		±100 nA
	1.77 1.74	2.1 V
	Min. 600	600 3.0

Isolated Tab

600V

60A

G = Gate E = Emitter C = Collector

Features

- Silocon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- Optimized for Low Conduction and Switching Losses
- 2500V~ Electrical Isolation
- Anti-Parallel Ultra Fast Diode
- Square RBSOA

Advantages

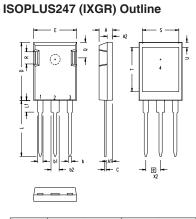
- High Power Density
- Low Gate Drive Requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

						Values	5
$(T_{J} = 25^{\circ})$	C, Unless C	therwise Specified		Min.	Тур.	Max	
g _{fs}	I _c = 3	0A, V _{CE} = 10V, Note 1	2	20	30		S
C _{ies})				2980		рF
C _{oes}	V _{CE} =	$25V, V_{GE} = 0V, f = 1MHz$	48N60B3		170		рF
	J		48N60B3D1	1	200		рF
res	·				45		pF
ک ^a)				115		nC
۵ _{ge}	$I_c = 4$	0A, $V_{GE} = 15V, V_{CE} = 0.5 \bullet$	V _{CES}		21		nC
¢ gc	J				40		nC
d(on))				22		ns
ri		tive Load, T _J = 25°C			25		ns
on		0A, V _{GE} = 15V			0.84		mJ
d(off)	$V_{CE} =$	480V, $R_{g} = 5\Omega$			130	200	ns
fi	Note	2			116	200	ns
off)				0.66	1.20	mJ
d(on))				19		ns
ri	Induc	tive Load, T _J = 125°C			25		ns
on	I _c = 3	0A, V _{GE} = 15V			1.71		mJ
d(off)	V _{CE} =	480V, R _g = 5Ω			190		ns
fi	Note	2			157		ns
off	J				1.30		mJ
R thJC						0.83	°C/W
R _{thCS}					0.15		°C/W

IXGR48N60B3 IXGR48N60B3D1



SYM	INCH	IES	MILLIMETERS		
214	MIN	MAX	MIN	MAX	
A	.190	.205	4.83	5.21	
A1	.090	.100	2.29	2.54	
A2	.075	.085	1.91	2.16	
σ	.045	.055	1.14	1.40	
b1	.075	.084	1.91	2.13	
b2	.115	.123	2.92	3.12	
С	.024	.031	0.61	0.80	
D	.819	.840	20.80	21.34	
Е	.620	.635	15.75	16.13	
е	.215	BSC	5.45 BSC		
Г	.780	.800	19.81	20.32	
L1	.150	.170	3.81	4.32	
Q	.220	.244	5.59	6.20	
R	.170	.190	4.32	4.83	
S	.520	.540	13.21	13.72	
Т	.620	.640	15.75	16.26	
U	.065	.080	1.65	2.03	

GATE DRAIN (COLLECTOR) SOURCE (EMITTER) 2 3

4 _ NO CONNECTION

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD except screw hole.

Reverse Diode (FRED) (D1 Version ONLY)

Symbol (T _J = 25°C	Test ConditionsCharaC, Unless Otherwise SpecifiedMin.	acteristic Typ.	cteristic Values Typ. Max.			
V _F	$I_{_{ m F}}$ = 30A, $V_{_{ m GE}}$ = 0V, Note 1 $T_{_{ m J}}$ = 150°C	1.6	2.8 V V			
I _{RM}	$I_{F} = 30A, V_{GE} = 0V, V_{R} = 100V$ - $di_{F}/dt = 100A/\mu s$ $I_{F} = 1A, -di/dt = 100A/\mu s, V_{R} = 30V$ $T_{J} = 100^{\circ}C$	4	A			
R _{thJC} R _{thCS}	$V_{\rm p} = 100 {\rm A}/\mu{\rm s}, V_{\rm p} = 300 {\rm V}^{-1}$	1.5	1.5 °C/W °C/W			

Notes:

- 1. Pulse test, t \leq 300µs, duty cycle, d \leq 2%.
- 2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

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IXYS MOSFETs and IGBTs are covered	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
by one or more of the following U.S. patents	: 4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	2 7,071,537	



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